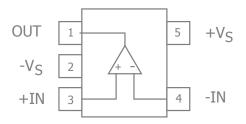
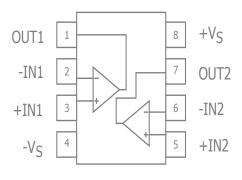
CLC1008 Pin Configuration



CLC1008 Pin Assignments

Pin No.	Pin Name	Description
1	OUT	Output
2	-V _S	Negative supply
3	+IN	Positive input
4	-IN	Negative input
5	+V _S	Positive supply

CLC2008 Pin Configuration



CLC2008 Pin Assignments

Pin No.	Pin Name	Description			
1	OUT1	Output, channel 1			
2	-IN1	Negative input, channel 1			
3	+IN1	+IN1 Positive input, channel 1			
4	-V _S	Negative supply			
5	+IN2	Positive input, channel 2			
6	-IN2	Negative input, channel 2			
7	OUT2	Output, channel 2			
8	+V _S	Positive supply			

Absolute Maximum Ratings

The safety of the device is not guaranteed when it is operated above the "Absolute Maximum Ratings". The device should not be operated at these "absolute" limits. Adhere to the "Recommended Operating Conditions" for proper device function. The information contained in the Electrical Characteristics tables and Typical Performance plots reflect the operating conditions noted on the tables and plots.

Parameter	Min	Max	Unit
Supply Voltage	0	6	V
Input Voltage Range	-V _s -0.5V	+V _S +0.5V	V
Continuous Output Current	-30	30	mA

Reliability Information

Parameter	Min	Тур	Max	Unit
Junction Temperature			175	°C
Storage Temperature Range	-65		150	°C
Lead Temperature (Soldering, 10s)			260	°C
Package Thermal Resistance				
5-Lead TSOT-5		215		°C/W
8-Lead SOIC		100		°C/W

Notes:

Package thermal resistance (θ_{JA}), JDEC standard, multi-layer test boards, still air.

Recommended Operating Conditions

Parameter	Min	Тур	Max	Unit
Operating Temperature Range	-40		+85	°C
Supply Voltage Range	2.5		5.5	V

Electrical Characteristics at +2.7V

 $T_A=25^{o}C,\,V_S=+2.7V,\,R_f=R_g=1k\Omega,\,R_L=1k\Omega$ to $V_S/2,\,G=2;$ unless otherwise noted.

Symbol	Parameter	Conditions	Min	Тур	Max	Units
Frequency D	omain Response	'				
UGBW _{SS}	Unity Gain -3dB Bandwidth	$G = +1$, $V_{OUT} = 0.05V_{pp}$, $R_f = 0$		65		MHz
BW _{SS}	-3dB Bandwidth	$G = +2, V_{OUT} < 0.2V_{pp}$		30		MHz
BW _{LS}	Large Signal Bandwidth	$G = +2$, $V_{OUT} = 2V_{pp}$		12		MHz
GBWP	Gain Bandwidth Product	$G = +11, V_{OUT} = 0.2V_{pp}$		28		MHz
Time Domain	n Response					
t _R , t _F	Rise and Fall Time	V _{OUT} = 0.2V step; (10% to 90%)		7.5		ns
t _S	Settling Time to 0.1%	V _{OUT} = 1V step		60		ns
OS	Overshoot	V _{OUT} = 1V step		10		%
SR	Slew Rate	2V step, G = -1		40		V/µs
Distortion/No	oise Response					
HD2	2nd Harmonic Distortion	V _{OUT} = 1V _{pp} , 1MHz		-67		dBc
HD3	3rd Harmonic Distortion	$V_{OUT} = 1V_{pp}$, 1MHz		-72		dBc
THD	Total Harmonic Distortion	V _{OUT} = 1V _{pp} , 1MHz		65		dB
e _n	Input Voltage Noise	> 10kHz		12		nV/√Hz
DC Performa	ince		<u>'</u>			
V _{IO}	Input Offset Voltage			0		mV
dV _{IO}	Average Drift			10		μV/°C
I _b	Input Bias Current			1.2		μΑ
dI _b	Average Drift			3.5		nA/°C
I _{OS}	Input Offset Current			30		nA
PSRR	Power Supply Rejection Ratio (1)	DC	60	66		dB
A _{OL}	Open-Loop Gain	$V_{OUT} = V_S / 2$		98		dB
I _S	Supply Current	per channel		470		μΑ
Input Charac	cteristics					
R _{IN}	Input Resistance	Non-inverting		9		ΜΩ
C_{IN}	Input Capacitance			1.5		pF
CMIR	Common Mode Input Range			-0.3 to 1.5		V
CMRR	Common Mode Rejection Ratio	DC, $V_{CM} = 0V \text{ to } V_S - 1.5$		74		dB
Output Char	acteristics					
	0.4	$R_L = 1k\Omega \text{ to } V_S/2$		0.09 to 2.53		V
V _{OUT}	Output Voltage Swing	$R_L = 10k\Omega$ to $V_S/2$		0.05 to 2.6		V
I _{OUT}	Output Current			±15		mA
I _{SC}	Short Circuit Output Current			±30		mA

Notes:

1. 100% tested at 25°C

Electrical Characteristics at +5V

 $T_A=25^{\circ}C,\,V_S=+5V,\,R_f=R_g=1k\Omega,\,R_L=1k\Omega$ to $V_S/2,\,G=2;$ unless otherwise noted.

Symbol	Parameter	Conditions	Min	Тур	Max	Units
Frequency D	omain Response	<u> </u>				
UGBW _{SS}	Unity Gain -3dB Bandwidth	$G = +1, V_{OUT} = 0.05V_{pp}, R_f = 0$		75		MHz
BW _{SS}	-3dB Bandwidth	$G = +2, V_{OUT} < 0.2V_{pp}$		35		MHz
BW _{LS}	Large Signal Bandwidth	$G = +2$, $V_{OUT} = 2V_{pp}$		15		MHz
GBWP	Gain Bandwidth Product	$G = +11, V_{OUT} = 0.2V_{pp}$		33		MHz
Time Domaii	n Response					
t _R , t _F	Rise and Fall Time	V _{OUT} = 0.2V step; (10% to 90%)		6		ns
t _S	Settling Time to 0.1%	V _{OUT} = 1V step		60		ns
OS	Overshoot	V _{OUT} = 1V step		12		%
SR	Slew Rate	2V step, G = -1		50		V/µs
Distortion/N	oise Response					
HD2	2nd Harmonic Distortion	V _{OUT} = 2V _{pp} , 1MHz		-64		dBc
HD3	3rd Harmonic Distortion	V _{OUT} = 2V _{pp} , 1MHz		-62		dBc
THD	Total Harmonic Distortion	V _{OUT} = 2V _{pp} , 1MHz		60		dB
e _n	Input Voltage Noise	> 10kHz		12		nV/√Hz
DC Performa	ince					
V _{IO}	Input Offset Voltage (1)		-5	-1	5	mV
dV _{IO}	Average Drift			10		μV/°C
I _b	Input Bias Current (1)		-3.5	1.2	3.5	μΑ
dI _b	Average Drift			3.5		nA/°C
I _{OS}	Input Offset Current (1)			30	350	nA
PSRR	Power Supply Rejection Ratio (1)	DC	60	66		dB
A _{OL}	Open-Loop Gain	$V_{OUT} = V_S / 2$	65	80		dB
I_S	Supply Current (1)	per channel		505	620	μΑ
Input Charac	cteristics					
R _{IN}	Input Resistance	Non-inverting		9		MΩ
C _{IN}	Input Capacitance			1.5		pF
CMIR	Common Mode Input Range			-0.3 to 3.8		V
CMRR	Common Mode Rejection Ratio (1)	DC, $V_{CM} = 0V \text{ to } V_S - 1.5$	65	74		dB
Output Char	acteristics					
V	Output Voltage Swing	$R_L = 1k\Omega$ to $V_S/2$ ⁽¹⁾	0.2 to 4.65	0.13 to 4.73		V
V _{OUT}	Output Voltage Swing	$R_L = 10k\Omega$ to $V_S/2$		0.08 to 4.84		V
I _{OUT}	Output Current			±15		mA
I_{SC}	Short Circuit Output Current			±30		mA

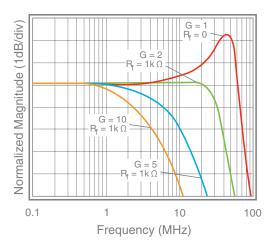
Notes:

1. 100% tested at 25°C

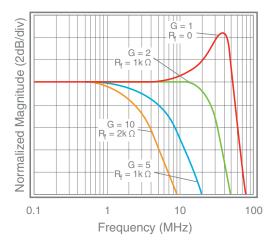
Typical Performance Characteristics

 $T_A = 25$ °C, $V_S = +5V$, $R_f = R_q = 1k\Omega$, $R_L = 1k\Omega$ to $V_S/2$, G = 2; unless otherwise noted.

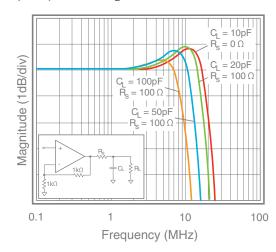
Non-Inverting Frequency Response



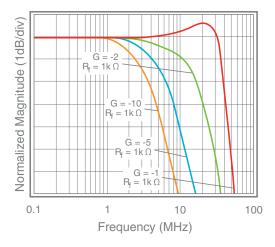
Non-Inverting Frequency Response at $V_S = 2.7V$



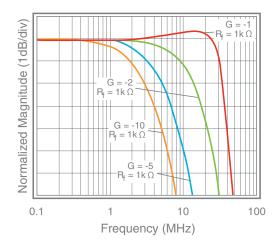
Frequency Response vs. C_L



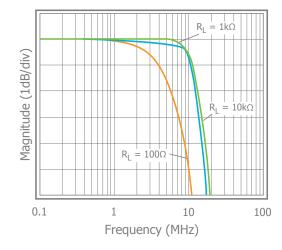
Inverting Frequency Response



Inverting Frequency Response at $V_S = 2.7V$



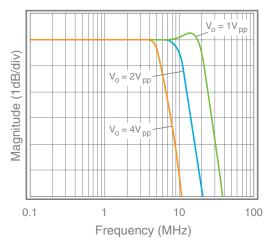
Frequency Response vs. R_L



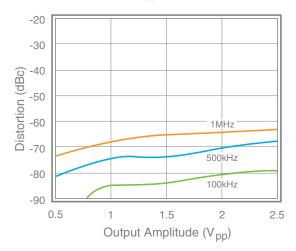
Typical Performance Characteristics

 $T_A = 25$ °C, $V_S = +5V$, $R_f = R_q = 1k\Omega$, $R_L = 1k\Omega$ to $V_S/2$, G = 2; unless otherwise noted.

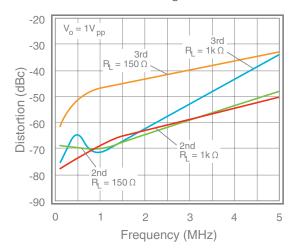
Frequency Response vs. V_{OUT}



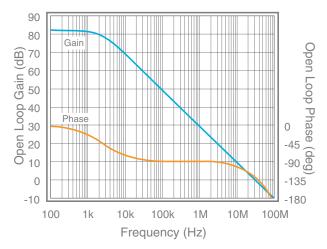
2nd Harmonic Distortion vs. V_{OUT}



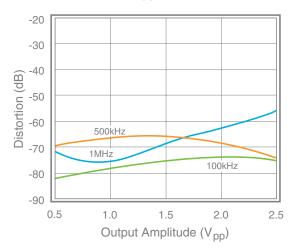
2nd & 3rd Harmonic Distortion at $V_S = 2.7V$



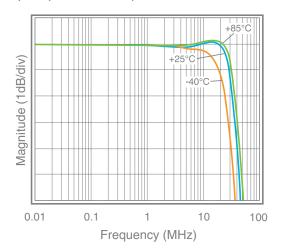
Open Loop Gain & Phase vs. Frequency



3rd Harmonic Distortion vs. V_{OUT}



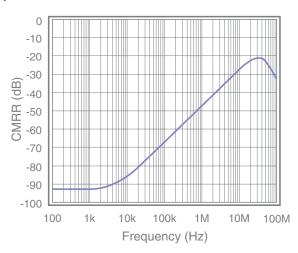
Frequency Response vs. Temperature



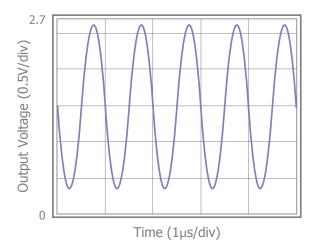
Typical Performance Characteristics - Continued

 $T_A=25$ °C, $V_S=+5V$, $R_f=R_g=1k\Omega$, $R_L=1k\Omega$ to $V_S/2$, G=2; unless otherwise noted.

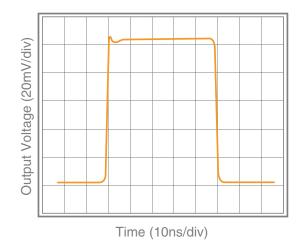
CMRR



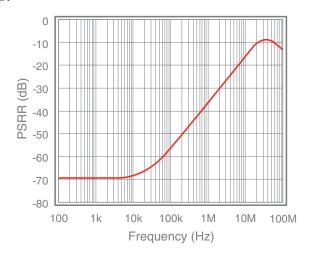
Output Swing at $V_S = 2.7V$, G=-1



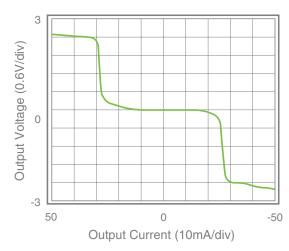
Small Signal Pulse Response at $V_S = 2.7V$



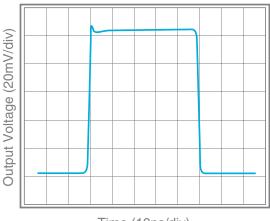
PSRR



Output Voltage vs. Output Current



Small Signal Pulse Response

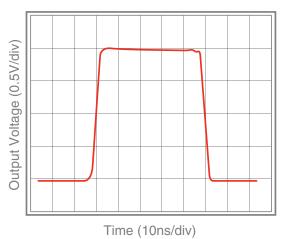


Time (10ns/div)

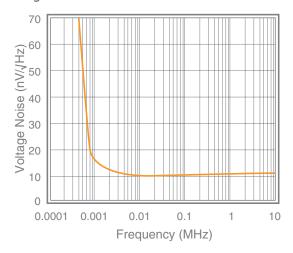
Typical Performance Characteristics - Continued

 $T_A=25^{\circ}C,\,V_S=+5V,\,R_f=R_g=1k\Omega,\,R_L=1k\Omega$ to $V_S/2,\,G=2;$ unless otherwise noted.

Large Signal Pulse Response



Input Voltage Noise



Application Information

General Description

The CLC1008 family are a single supply, general purpose, voltage-feedback amplifiers fabricated on a complementary bipolar process. The CLC1008 offers 75MHz unity gain bandwidth, 50V/µs slew rate, and only 505µA supply current. It features a rail-to-rail output stage and is unity gain stable.

Figures 1, 2, and 3 illustrate typical circuit configurations for non-inverting, inverting, and unity gain topologies for dual supply applications. They show the recommended bypass capacitor values and overall closed loop gain equations. Figure 4 shows the typical non-inverting gain circuit for single supply applications.

The common mode input range extends to 300mV below ground in single supply operation. Exceeding these values will not cause phase reversal. However, if the input voltage exceeds the rails by more than 0.5V, the input ESD devices will begin to conduct.

The design uses a Darlington output stage. The output stage is short circuit protected and offers "soft" saturation protection that improves recovery time.

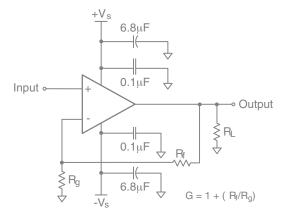


Figure 1. Typical Non-Inverting Gain Circuit

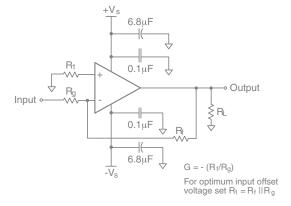


Figure 2. Typical Inverting Gain Circuit

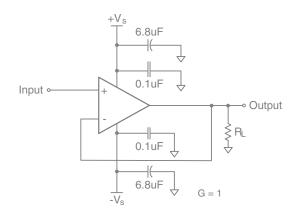


Figure 3. Unity Gain Circuit

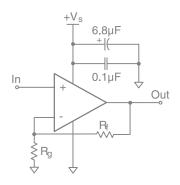


Figure 4. Single Supply Non-Inverting Gain Circuit

For optimum response at a gain of +2, a feedback resistor of $1k\Omega$ is recommended. Figure 5 illustrates the CLC1008 frequency response with both $1k\Omega$ and $2k\Omega$ feedback resistors.

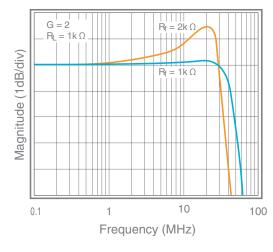


Figure 5. Frequency Response vs. Rf

Power Dissipation

Power dissipation should not be a factor when operating under the stated 1k ohm load condition. However, applications with low impedance, DC coupled loads should be analyzed to ensure that maximum allowed junction temperature is not exceeded. Guidelines listed below can be used to verify that the particular application will not cause the device to operate beyond it's intended operating range.

Maximum power levels are set by the absolute maximum junction rating of 150°C. To calculate the junction temperature, the package thermal resistance value Theta_{JA} (Θ_{JA}) is used along with the total die power dissipation.

$$T_{Junction} = T_{Ambient} + (\Theta_{JA} \times P_{D})$$

Where T_{Ambient} is the temperature of the working environment.

In order to determine P_D , the power dissipated in the load needs to be subtracted from the total power delivered by the supplies.

$$P_D = P_{supply} - P_{load}$$

Supply power is calculated by the standard power equation.

$$P_{supply} = V_{supply} \times I_{RMS supply}$$

 $V_{supply} = V_{S+} - V_{S-}$

Power delivered to a purely resistive load is:

$$P_{load} = ((V_{l OAD})_{RMS^2})/Rload_{eff}$$

The effective load resistor (Rload_{eff}) will need to include the effect of the feedback network. For instance,

Rloadeff in Figure 3 would be calculated as:

$$R_L \parallel (R_f + R_a)$$

These measurements are basic and are relatively easy to perform with standard lab equipment. For design purposes however, prior knowledge of actual signal levels and load impedance is needed to determine the dissipated power. Here, P_D can be found from

$$P_D = P_{Quiescent} + P_{Dynamic} - P_{Load}$$

Quiescent power can be derived from the specified I_S values along with known supply voltage, V_{Supply} . Load power can be calculated as above with the desired signal amplitudes using:

$$(V_{LOAD})_{RMS} = V_{PEAK} / \sqrt{2}$$

$$(I_{LOAD})_{RMS} = (V_{LOAD})_{RMS} / Rload_{eff}$$

The dynamic power is focused primarily within the output stage driving the load. This value can be calculated as:

$$P_{DYNAMIC} = (V_{S+} - V_{LOAD})_{RMS} \times (I_{LOAD})_{RMS}$$

Assuming the load is referenced in the middle of the power rails or $V_{\text{supply}}/2$.

The CLC1008 is short circuit protected. However, this may not guarantee that the maximum junction temperature (+150°C) is not exceeded under all conditions. Figure 6 shows the maximum safe power dissipation in the package vs. the ambient temperature for the packages available.

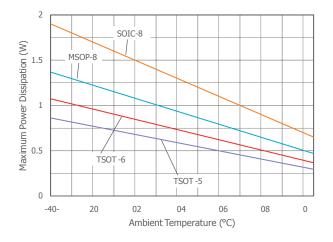


Figure 6. Maximum Power Derating

Driving Capacitive Loads

Increased phase delay at the output due to capacitive loading can cause ringing, peaking in the frequency response, and possible unstable behavior. Use a series resistance, R_{S} , between the amplifier and the load to help improve stability and settling performance. Refer to Figure 7.

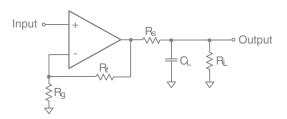


Figure 7. Addition of R_S for Driving Capacitive Loads

Table 1 provides the recommended R_{S} for various capacitive loads. The recommended R_{S} values result in

approximately <1dB peaking in the frequency response. The Frequency Response vs. C_L plot, on page 4, illustrates the response of the CLCx008.

C _L (pF)	R _S (Ω)	-3dB BW (kHz)
10pF	0	22
20pF	100	19
50pF	100	12
100pF	100	10.2

Table 1: Recommended R_S vs. C_L

For a given load capacitance, adjust R_S to optimize the tradeoff between settling time and bandwidth. In general, reducing R_S will increase bandwidth at the expense of additional overshoot and ringing.

Overdrive Recovery

An overdrive condition is defined as the point when either one of the inputs or the output exceed their specified voltage range. Overdrive recovery is the time needed for the amplifier to return to its normal or linear operating point. The recovery time varies, based on whether the input or output is overdriven and by how much the range is exceeded. The CLC1008 and CLC2008 will typically recover in less than 20ns from an overdrive condition. Figure 8 shows the CLC1008 in an overdriven condition.

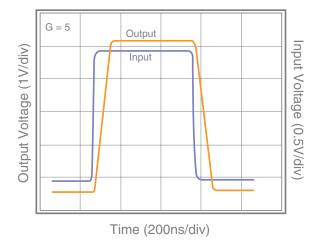


Figure 8. Overdrive Recovery

Layout Considerations

General layout and supply bypassing play major roles in

high frequency performance. Exar has evaluation boards to use as a guide for high frequency layout and as an aid in device testing and characterization. Follow the steps below as a basis for high frequency layout:

- Include 6.8µF and 0.1µF ceramic capacitors for power supply decoupling
- Place the 6.8µF capacitor within 0.75 inches of the power pin
- Place the 0.1µF capacitor within 0.1 inches of the power pin
- Remove the ground plane under and around the part, especially near the input and output pins to reduce parasitic capacitance
- Minimize all trace lengths to reduce series inductances

Refer to the evaluation board layouts below for more information.

Evaluation Board Information

The following evaluation boards are available to aid in the testing and layout of these devices:

Evaluation Board	Products
CEB002	CLC1008 in TSOT-5
CEB003	CLC1008 in SOIC-8
CEB006	CLC2008 in SOIC-8

Evaluation Board Schematics

Evaluation board schematics and layouts are shown in Figures 8-14. These evaluation boards are built for dual-supply operation. Follow these steps to use the board in a single-supply application:

- 1. Short -Vs to ground.
- 2. Use C3 and C4, if the $\mbox{-V}_{\mbox{\scriptsize S}}$ pin of the amplifier is not directly connected to the ground plane.

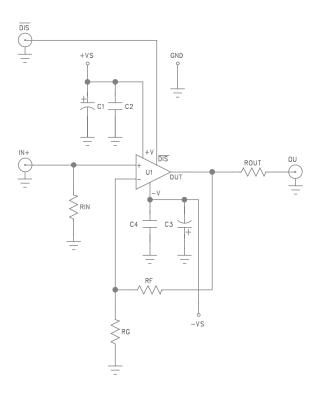


Figure 8. CEB002 & CEB003 Schematic

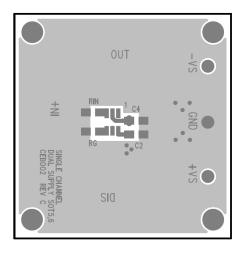


Figure 9. CEB002 Top View

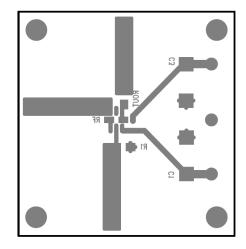


Figure 10. CEB002 Bottom View

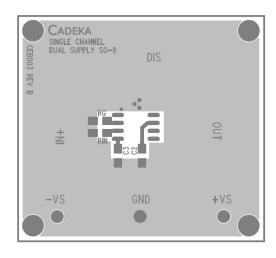


Figure 11. CEB003 Top View

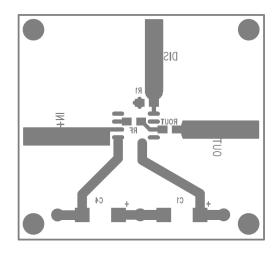


Figure 12. CEB003 Bottom View

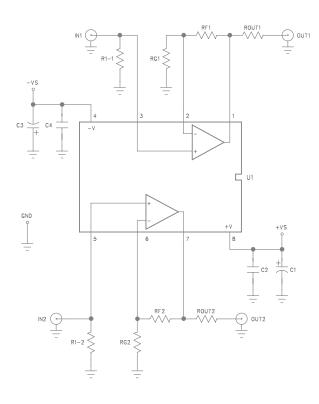


Figure 13. CEB006

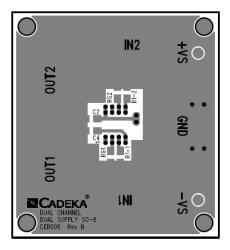


Figure 14. CEB006 Top View

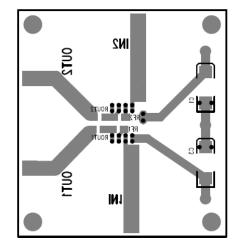
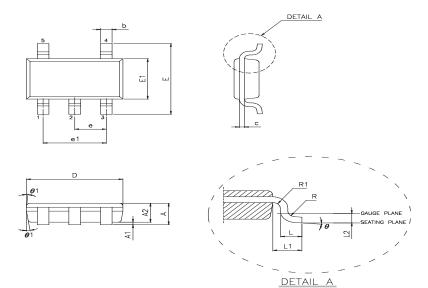


Figure 15. CEB006 Bottom View

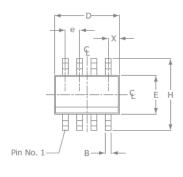
Mechanical Dimensions

TSOT-5 Package

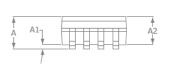


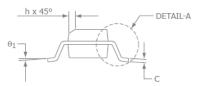
5 Pin TSOT (OPTION 2)						
SYMBOLS	DIMENSION IN MM (Control Unit)			DIMENSION IN INCH (Reference Unit)		
	MIN	NOM	MAX	MIN	NOM	MAX
А	0.75	_	0.80	0.030	_	0.031
A1	0.00	_	0.05	0.000	_	0.002
A2	0.70	0.75	0.78	0.028	0.030	0.031
ь	0.35	_	0.50	0.012	_	0.020
С	0.10	_	0.20	0.003	_	0.008
D	2	.90 BS	SC .	C).114 B	SC
E	2.80 BSC			0.110 BSC		
E1	1	.60 BS	SC .	0.063 BSC		
е	C	.95 BS	SC SC	0.038 BSC		
e1	1	.90 BS	SC .	C	0.075 B	SC
L	0.37	0.45	0.60	0.012	0.018	0.024
L1	().60 RE	F	0	.024 RE	F
L2	C).25 BS	SC .	0	.010 BS	C
R	0.10	_	_	0.004		
R1	0.10	-	0.25	0.004	_	0.010
θ	0,	4°	8°	0°	4°	8°
θ1	4°	10°	12°	4°	10°	12°
N		5			5	

SOIC-8 Package









SOIC-8					
SYMBOL	MIN	MAX			
A1	0.10	0.25			
В	0.36	0.48			
С	0.19	0.25			
D	4.80	4.98			
Е	3.81	3.99			
е	1.27	BSC			
Н	5.80	6.20			
h	0.25	0.5			
L	0.41	1.27			
Α	1.37	1.73			
θ1 0°		80			
Х	X 0.55 ref				
θ2	7º BSC				

- All dimensions are in millimeters.
 Lead coplanarity should be 0 to 0.1mm (0.004") max.
- 3. Package surface finishing: VDI 24~27
- 4. All dimension excluding mold flashes.
- 5. The lead width, B to be determined at 0.1905mm from the lead tip.

Revision History

Revision	Date	Description
2C.R	July 2018	Updated to Resurgent Semiconductor.

For Further Assistance:

www.resurgentsemi.net



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